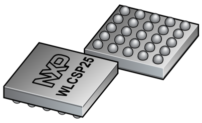
SOT1401-4

wafer level chip-scale package, 25 balls; 0.4 mm pitch, 2.09 mm x 2.09 mm x 0.525 mm body

29 January 2026

Package information



1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP25
Package type industry code	WLCSP25
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	03-08-2018
Manufacturer package code	98ASA01151D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.06	2.09	2.12	mm
package width	2.06	2.09	2.12	mm
package height	-	0.525	0.565	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	25	-	

2 Package outline

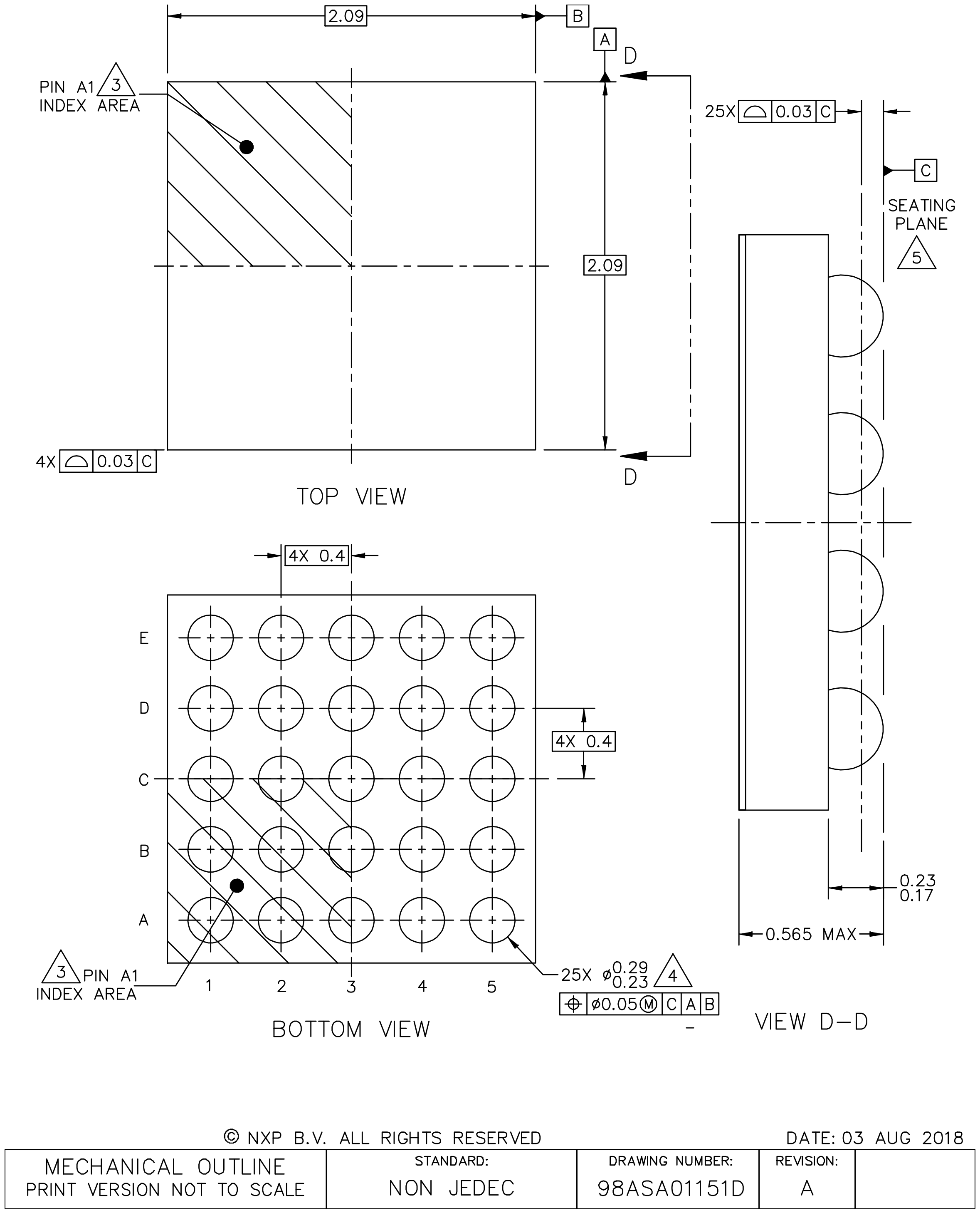
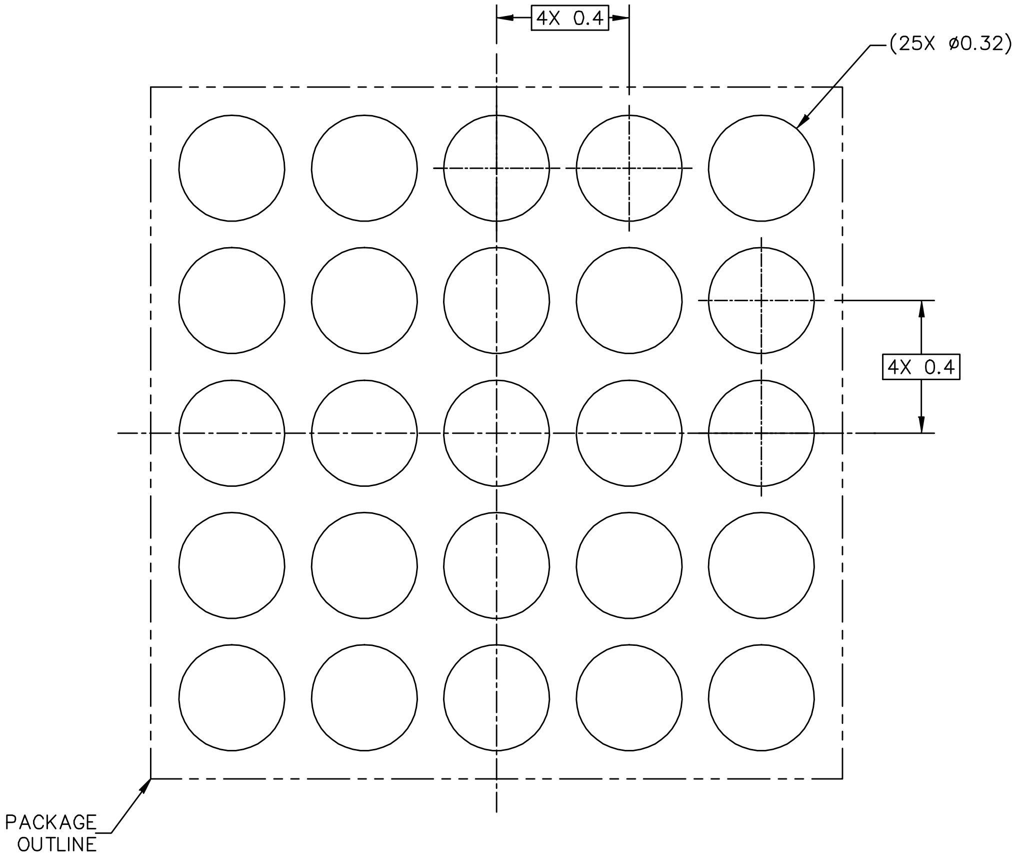


Figure 1. Package outline WLCSP25 (SOT1401-4)

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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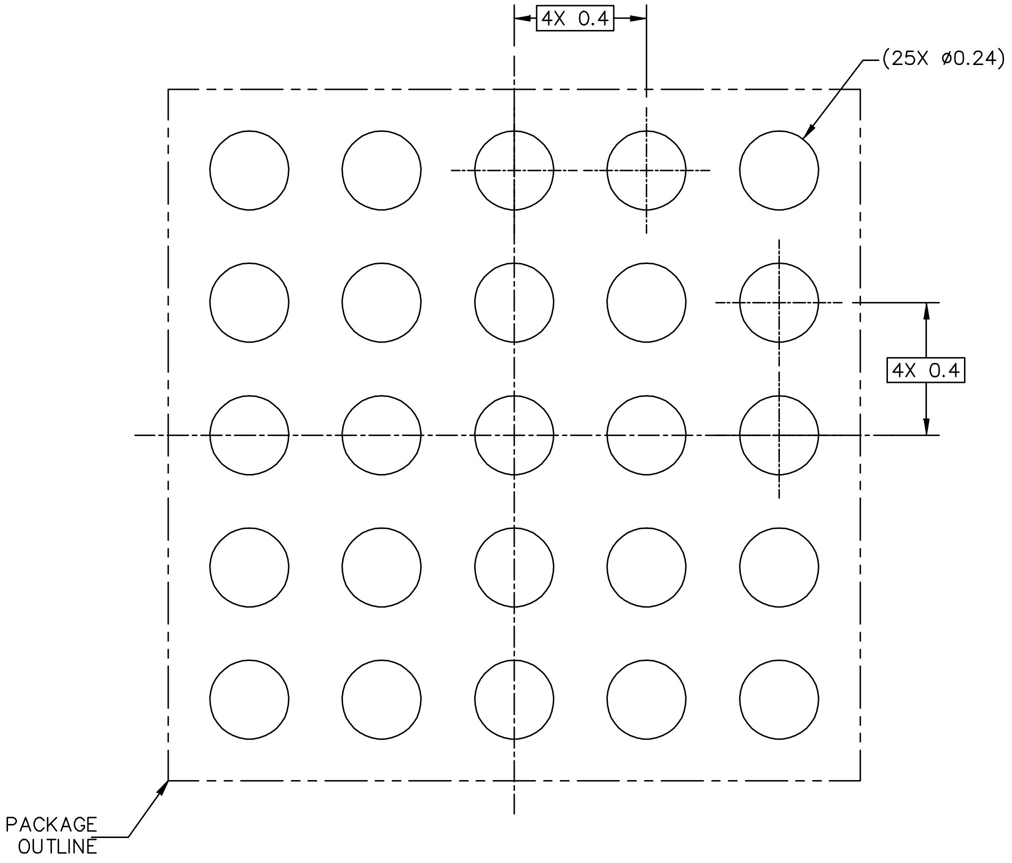
DATE: 03 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01151D	REVISION: A	

Figure 2. Reflow soldering footprint part1 for WLCSP25 (SOT1401-4)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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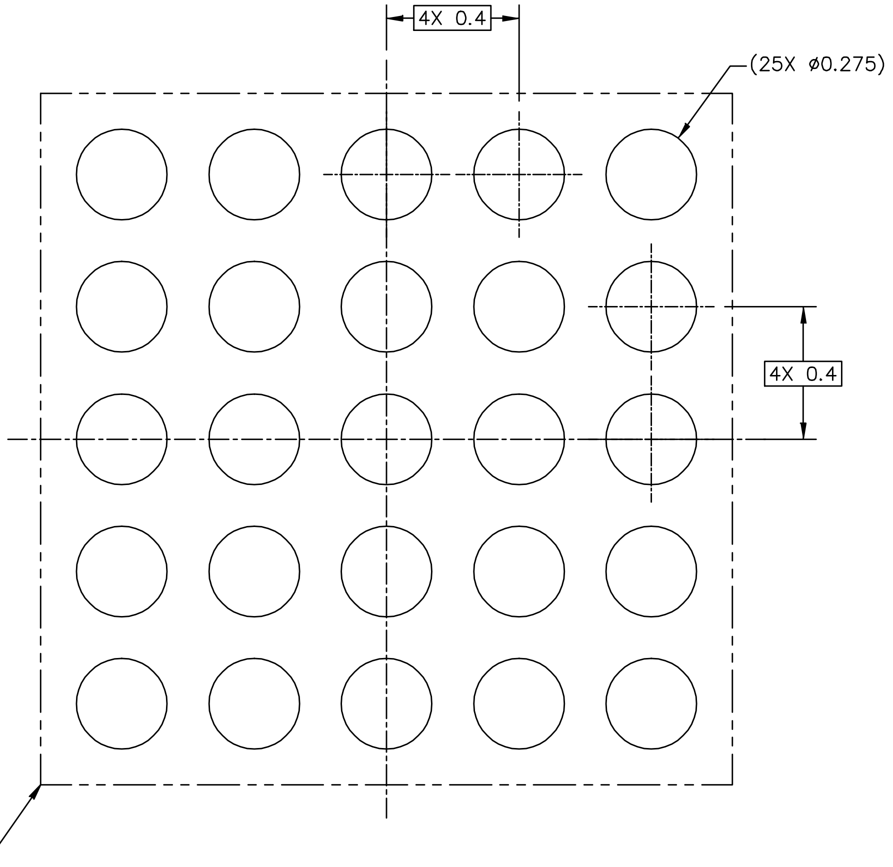
DATE: 03 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01151D	REVISION: A	

Figure 3. Reflow soldering footprint part2 for WLCSP25 (SOT1401-4)



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 03 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01151D	REVISION: A	

Figure 4. Reflow soldering footprint part3 for WLCSP25 (SOT1401-4)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

DATE: 03 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD:	DRAWING NUMBER:	REVISION:	
	NON JEDEC	98ASA01151D	A	

Figure 5. Package outline note WLCSP25 (SOT1401-4)

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